

## ABSTRACT

An LTCC (low temperature cofired ceramic) structure which has conductors to which leads are to be bonded for connection to external circuitry. The conductors include additives to promote adhesion to the ceramic layer. The presence of these additives degrade bonding performance. For better bondability of the leads, a pure conductor metal layer, devoid of the additives is placed on the conductors in areas where leads are to be bonded. This pure conductor metal layer may be cofired with the stack of ceramic layers or may be post fired after stack firing.